Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **I0110-01** DATE: 10/19/01
Product Affected: IDT79RC32V332-XXXDP

Date Effective: 1/19/02

MEANS OF DISTINGUISHING CHANGED DEVICES:
■ Product Mark Package designator change from DP to DH
☐ Back Mark
☐ Date Code
☐ Other

Contact: Bimla Paul
Title: Product Assurance Manager
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E-mail: bimla.paul@idt.com

Attachment:: ■ Yes ☐ No

Samples: Available Upon Request

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
■ Material
☐ Testing
☐ Manufacturing Site
☐ Data Sheet
☐ Other

To convert 208 PQFP (DP) with exposed heat slug package to 208 PQFP (DH) package with internal Heat Spreader.
The ordering part# will change from IDT79RC32V332-XXXDP to IDT79RC32V332-XXXDH
This conversion should not require any board layout changes since the foot print for these two packages are identical.

RELIABILITY/QUALIFICATION SUMMARY:

Qualification and reliability data is attached.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ____________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ____________________

E-Mail Address: ____________________

Title: ____________________

Phone# /Fax# : ____________________

CUSTOMER COMMENTS: ____________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ____________________ DATE: ____________________

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ATTACHMENT - PCN # I0110-01

PCN Summary

To convert 208 PQFP (DP) with exposed heat slug package to 208 PQFP (DH) package with internal Heat Spreader.

This conversion should not require any board layout changes since the foot print for these two packages are identical.

Detail of Change

	Old Package (DP)	New Package DH (208 QFP with Heat Spreader)
Mold compound	KMC184-9	KMC184-9
Die Attach	8361J (ABELESTIK)	8390 (ABELESTIK)
Wire Bond	1.3 mil Au	1.3 mil Au
Lead Finish	Solder Plate	Solder Plate
Heat Spreader	Exposed Heat slug	Internal Heat spreader
Thermal Characteristics	Theta Jc = 2.4 °C/W Theta Ja = 17 °C/W	Theta Jc = 6.4 °C/W Theta Ja = 19.4 °C/W
Assembly Location	IDT Penang (Malaysia)	IDT Penang (Malaysia)
Package Thickness	3.4 mm	3.4 mm

Conversion schedule (Estimated)

	Sample Availability	**Production Shipments**
IDT79RC32V332-XXXDH	Available	1/19/02

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Qualification Results

Test Vehicle: 79RC32V332

	Sample Size/ Rejects
Package Moisture Characterization (Level 3)	11/0
Physical Dimension : Mil-std 883, Method 2016	5/0
Bake and Ball Shear Test	5/0
Wire Pull Test	5/0
Internal Visual Inspection, Mil-std 883, Method 2009	5/0
External Visual Inspection,Mil-std 883, Method 2010	25/0
S.A.T./Dye Penetration Test	10/0
X-ray Examination	45/0

Characterization Data:

Characterization Data is available upon request.